

Part Number: **DxG-T**
Weight (mg): 130

RoHS Exemptions 5 & 7a
applied x= 1, 2, 3, 4, 5, 6, 7

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	96.49%	0.28	0.37	964900	2846
		PbO	1317-36-8	2.43			2430000	0
		Ni	7440-02-0	1.08%			10800	0
Leadframe	Copper Alloy	Cu	7440-50-8	97.45%	73.60	95.68	974500	736000
		Fe	7439-89-6	2.40%			24000	0
		P	7723-14-0	0.03%			300	0
		Zn	7440-66-6	0.12%			1200	0
		Lead	7439-92-1	92.50%			925000	24692
Die Attach Solder	RoHS Exempt High Temperature	Sn	7440-31-5	5.00%	2.47	3.21	50000	0
		Silver	7440-22-4	2.50%			25000	0
		Silica (SiO ₂) (60~90%)	14808-60-7	75.00%			750000	226462
Encapsulation	EME-1200	Polymer with 1-chloro-2,3-epoxypropane and 5-bromo-1,4-dioxane (10~17%)	29690-82-2	13.50%	22.65	29.44	135000	0
		Phenol-formaldehyde polymer (5~10%)	9003-35-4	7.50%			75000	0
		TBBA-diglycidyl-ether oligomer (1~2%)	40039-93-8	1.50%			15000	0
		Sb ₂ O ₃ (0~5%)	1309-64-4	2.50%			25000	0
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.00	1.30	1000000	10000
				Total	100.00	130.00		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate